



### CST100N03D N-Ch 30V Fast Switching MOSFETs

- ★ Super Low Gate Charge
- ★ 100% EAS Guaranteed
- ★ Green Device Available
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

#### CST100N03D Product Summary

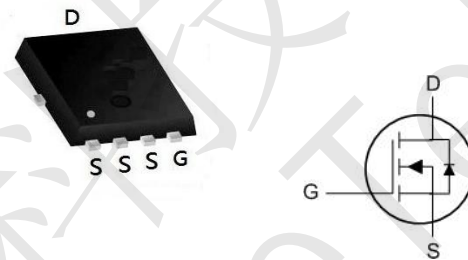


BVDSS	RDSON	ID
30V	3.5mΩ	100A

#### CST100N03D Description

The CST100N03D is the high cell density trenched N-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications. The CST100N03D meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

#### CST100N03D PDFN3333-8L Pin Configuration



#### CST100N03D Absolute Maximum Ratings

Symbol	Parameter	Rating		Units
		10s	Steady State	
$V_{DS}$	Drain-Source Voltage	30		V
$V_{GS}$	Gate-Source Voltage	$\pm 20$		V
$I_D@T_C=25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	100		A
$I_D@T_C=100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	50		A
$I_D@T_A=25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	30	19	A
$I_D@T_A=70^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	25	16	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	162		A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	144.7		mJ
$I_{AS}$	Avalanche Current	53.8		A
$P_D@T_C=25^\circ C$	Total Power Dissipation <sup>4</sup>	62.5		W
$P_D@T_A=25^\circ C$	Total Power Dissipation <sup>4</sup>	6	2.42	W
$T_{STG}$	Storage Temperature Range	-55 to 175		$^\circ C$
$T_J$	Operating Junction Temperature Range	-55 to 175		$^\circ C$

#### CST100N03D Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	---	62	$^\circ C/W$
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup> ( $t \leq 10s$ )	---	25	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	---	2.4	$^\circ C/W$



#### CST100N03D Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	30	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 30V, V <sub>GS</sub> = 0V,	-	-	1.0	μA
I <sub>GSS</sub>	Gate to Body Leakage Current	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±20V	-	-	±100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	1.0	1.5	2.5	V
R <sub>DS(on)</sub>	Static Drain-Source on-Resistance note3	V <sub>GS</sub> = 10V, I <sub>D</sub> = 30A	-	3.5	4.7	mΩ
		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 20A	-	6.0	10	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 15V, V <sub>GS</sub> = 0V, f = 1.0MHz	-	2100	-	pF
C <sub>oss</sub>	Output Capacitance		-	326	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		-	282	-	pF
Q <sub>g</sub>	Total Gate Charge		-	45	-	nC
Q <sub>gs</sub>	Gate-Source Charge	V <sub>DS</sub> = 15V, I <sub>D</sub> = 30A, V <sub>GS</sub> = 10V	-	3	-	nC
Q <sub>gd</sub>	Gate-Drain("Miller") Charge		-	15	-	nC
t <sub>d(on)</sub>	Turn-on Delay Time	V <sub>DS</sub> = 15V, I <sub>D</sub> = 30A, R <sub>GEN</sub> = 3Ω, V <sub>GS</sub> = 10V	-	21	-	ns
t <sub>r</sub>	Turn-on Rise Time		-	32	-	ns
t <sub>d(off)</sub>	Turn-off Delay Time		-	59	-	ns
t <sub>f</sub>	Turn-off Fall Time		-	34	-	ns
I <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current		-	-	50	A
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current		-	-	200	A
V <sub>SD</sub>	Drain to Source Diode Forward Voltage	V <sub>GS</sub> = 0V, I <sub>S</sub> = 30A	-	-	1.2	V
t <sub>rr</sub>	Body Diode Reverse Recovery Time	I <sub>F</sub> = 20A, dI/dt = 100A/μs	-	15	-	ns
Q <sub>rr</sub>	Body Diode Reverse Recovery Charge		-	4	-	nC

Notes: 1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

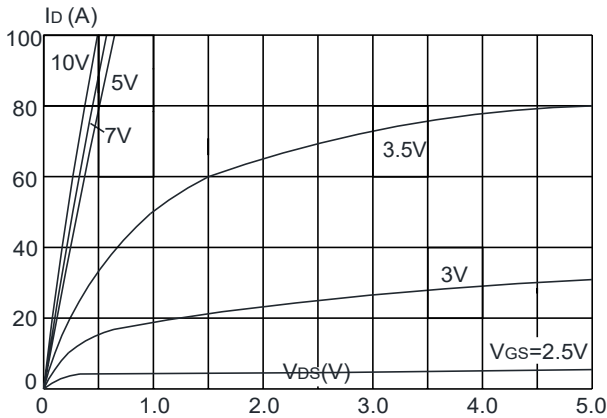
2. EAS condition: T<sub>J</sub> = 25°C, V<sub>G</sub> = 10V, R<sub>G</sub> = 25Ω, L = 0.5mH, I<sub>AS</sub> = 18.4A

3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 0.5%

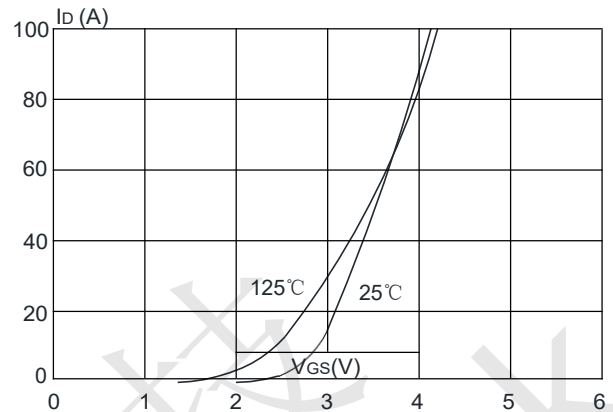


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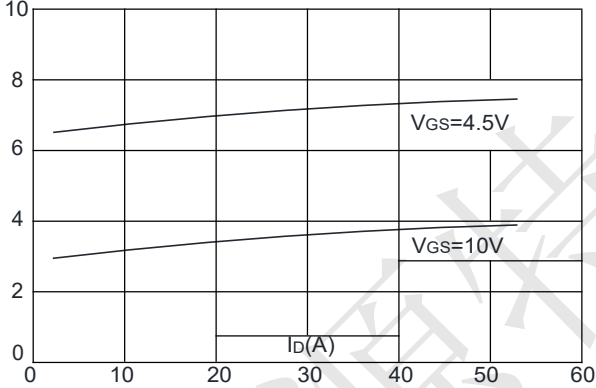
**Figure 1: Output Characteristics**



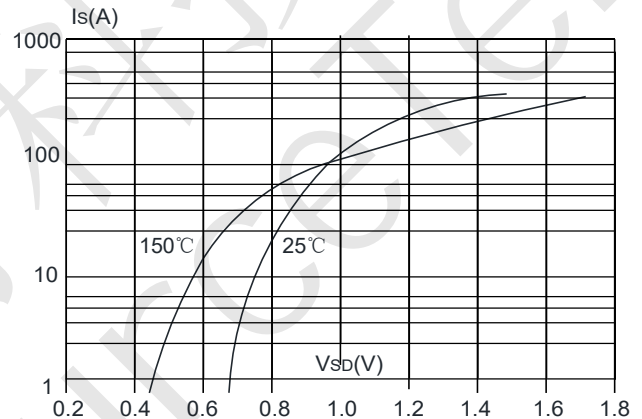
**Figure 2: Typical Transfer Characteristics**



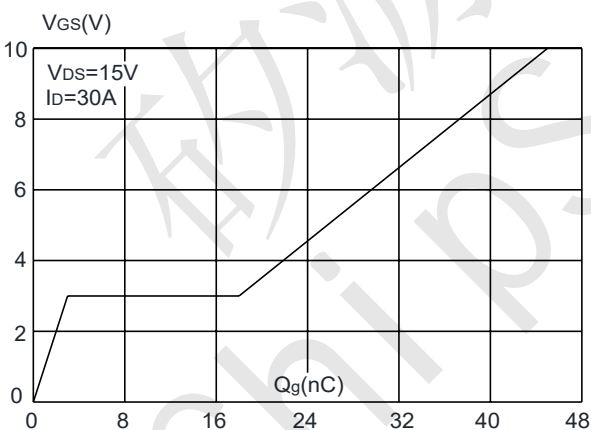
**Figure 3: On-resistance vs. Drain Current**



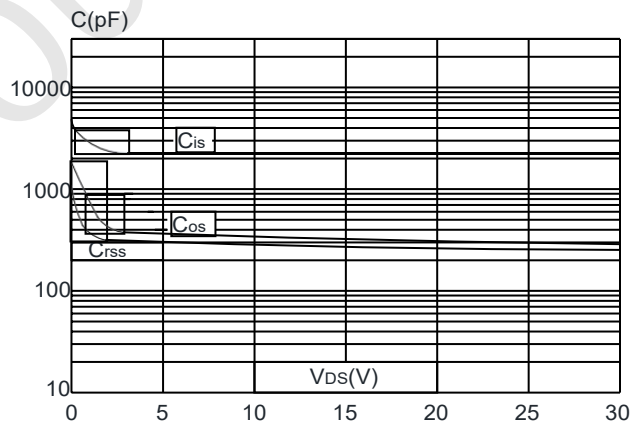
**Figure 4: Body Diode Characteristics**



**Figure 5: Gate Charge Characteristics**



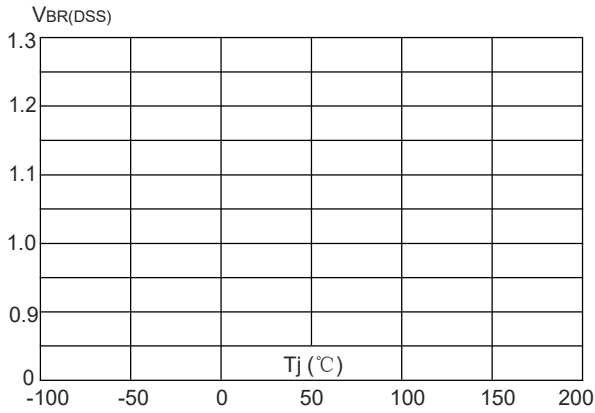
**Figure 6: Capacitance Characteristics**



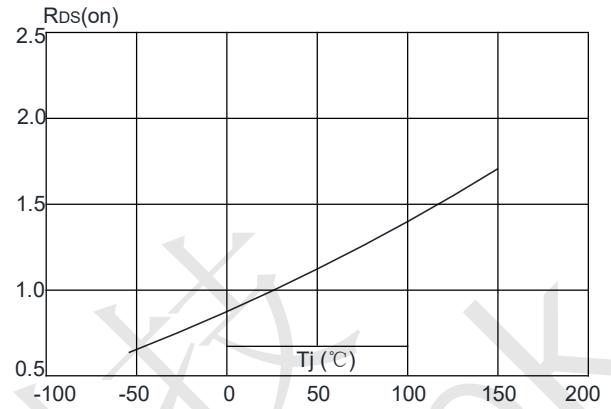


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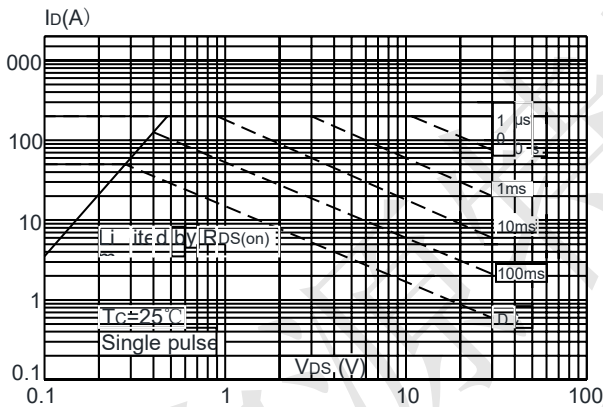
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



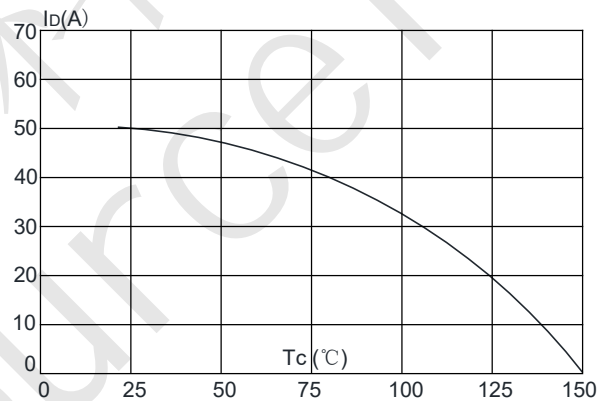
**Figure 8:** Normalized on Resistance vs. Junction Temperature



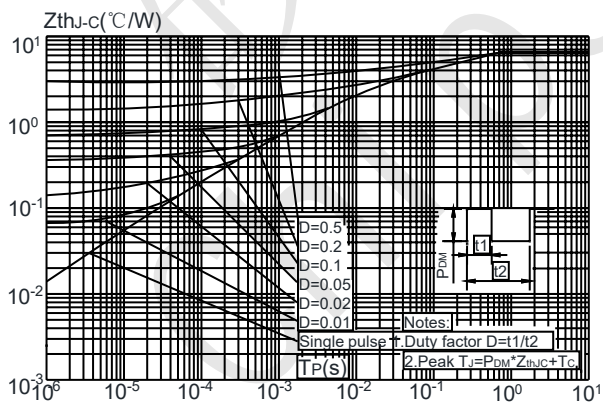
**Figure 9:** Maximum Safe Operating Area



**Figure 10:** Maximum Continuous Drain Current vs. Case Temperature



**Figure.11:** Maximum Effective Transient Thermal Impedance, Junction-to-Case (PDFN3.3\*3.3-8L)





### CST100N03D Test Circuit

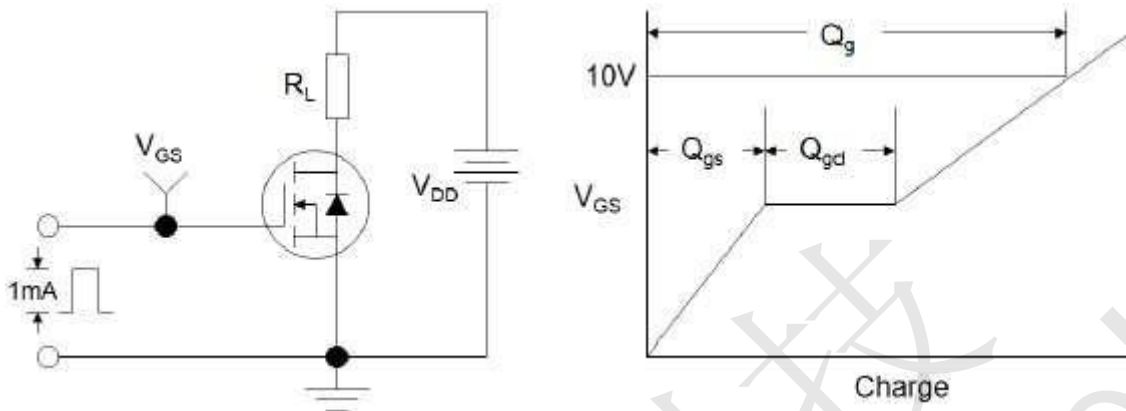


Figure1:Gate Charge Test Circuit & Waveform

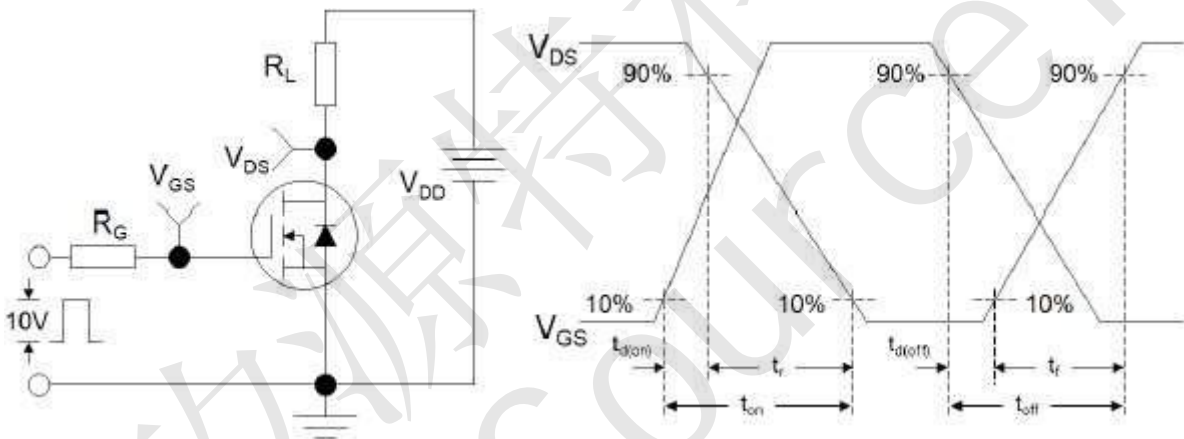


Figure 2: Resistive Switching Test Circuit & Waveforms

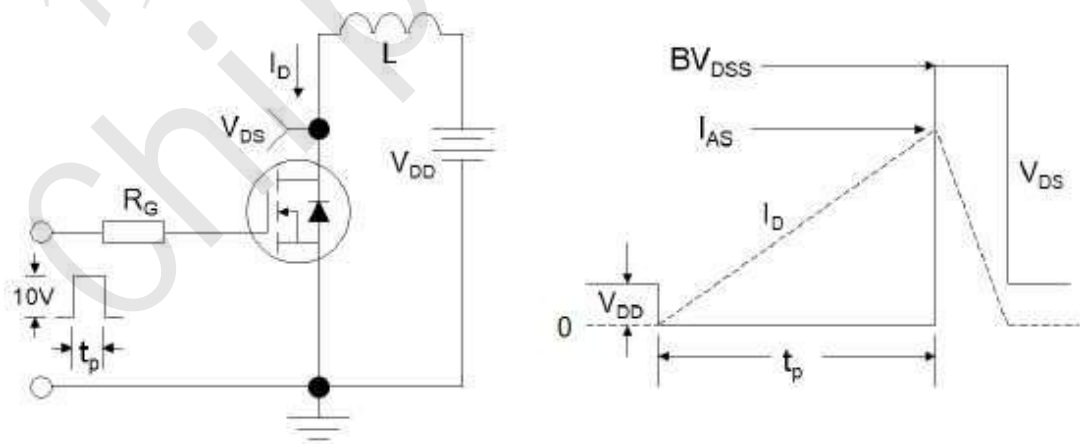
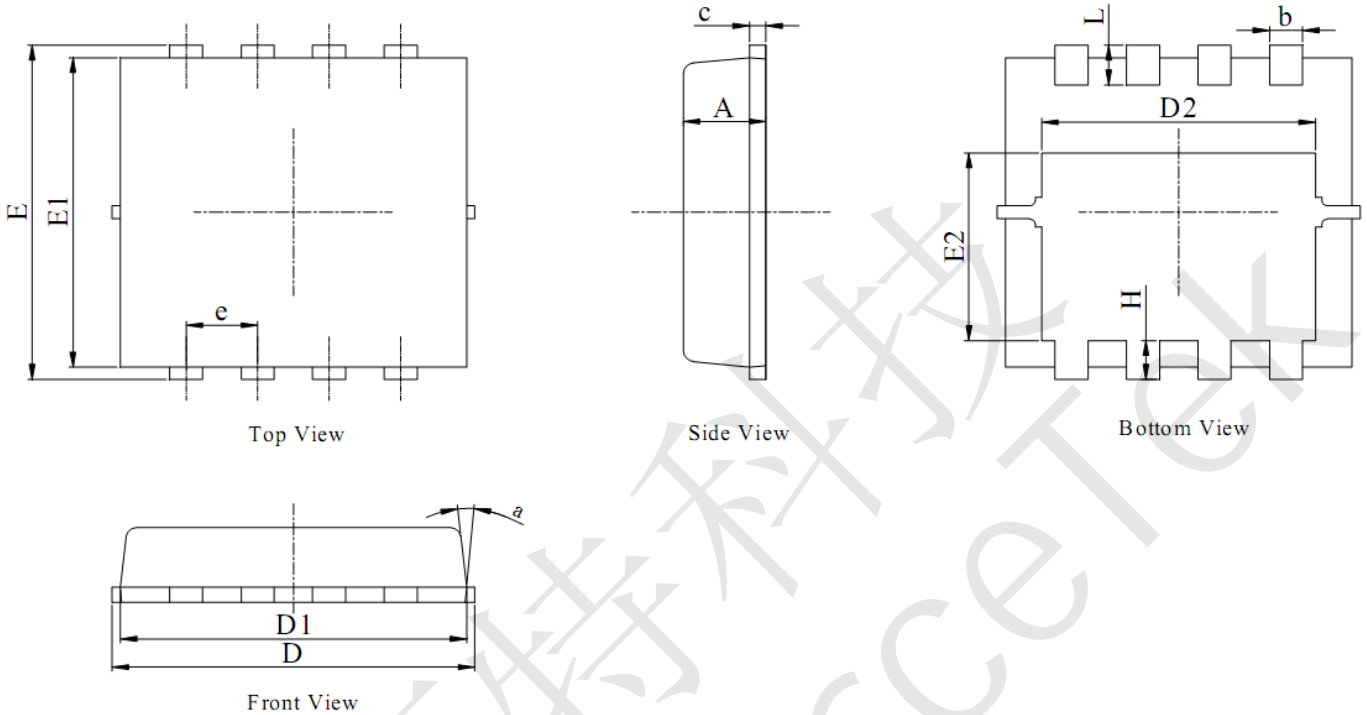


Figure 3:Unclamped Inductive Switching Test Circuit & Waveforms



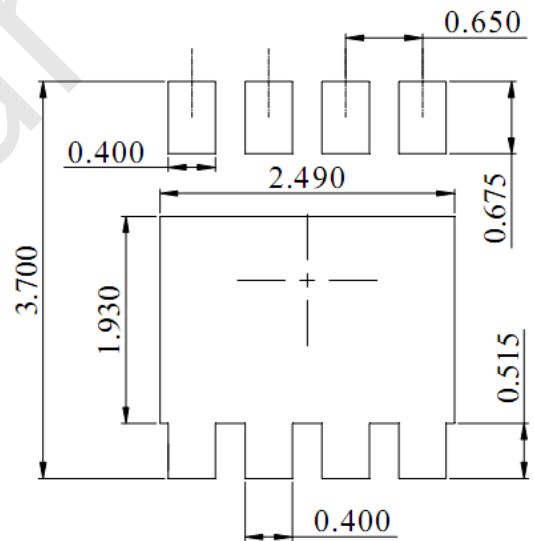
#### CST100N03D Package Mechanical Data-PDFN3333-8L-Single



**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M,1994.
2. ALL DIMENSIONS IN MILLIMETER (ANGLE IN DEGREE).
3. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD FLASH PROTRUSIONS OR GATE BURRS.

DIM.	MILLIMETER		
	MIN.	NOM.	MAX.
A	0.70	0.75	0.80
b	0.25	0.30	0.35
c	0.10	0.20	0.25
D	3.00	3.15	3.25
D1	2.95	3.05	3.15
D2	2.39	2.49	2.59
E	3.20	3.30	3.40
E1	2.95	3.05	3.15
E2	1.70	1.80	1.90
e	0.65 BSC		
H	0.30	0.40	0.50
L	0.25	0.40	0.50
a	---	---	15°



DIMENSIONS: MILLIMETERS